Amphenol
COMMUNICATIONS SOLUTIONS

Product/Process Change Notifications

Amphenol Commercial Products

PCN - 26 127

www.amphenol-cs.com

Release Date: July 28 2026

Product Name:	HPL – 629	
	Microspeed RA Combo	
Product Manager:	Chen Bruce	
Subject:	Notification of Planned Change	
Distribution:	Affected customers	
Type of Change:	Location Change	
Change Description:	1. Addition of new stamping and plating capability and material localization for Amphenol Nantong site. 2. Localization with alternate materials for the Combo connection plate. Change of contact material from C75700(CuNi12Zn24) to C75200(CuNi18Zn18)	
Reason for Change:	1. For capacity enhancement, the component can be sourced from existing Amphenol FCI Besancon France site and locally in China for Amphenol Nantong site. 2. To mitigate shortage of contact raw materials, introduced alternate similar material source.	
Affected Parts:	See Affected Parts.xls	
Effective Date of Change:	October,15 2026	
Last Time Buy Date:	NA	
Earliest Disty Return Date:	NA	
Last Time Shipment Date	NA	
Datasheet Attached?	Yes	
Qual/Test Data Attached?	Yes	
Samples Availability Date:	30 September ,2026	
Available Alternatives?		
Questions?	*Contact your local ACS Representative, or Product Manager*	
	Chen Bruce / Product Manager	
	Bruce.Chen@amphenol-fci.com	

Note:
Customers should contact Product Line Manager (or their local Amphenol Representative) directly regarding any concern on the PCN.
Lack of any such customer feedback within three weeks of PCN release date will be interpreted as non-objection .